SPECIFICATIONS (T_J = 25 °C, unless otherwise noted)						
PARAMETER	**SYMBOL**	**TEST CONDITIONS**	**MIN.**	**TYP.**	**MAX.**	**UNIT**
Static						
Drain-source breakdown voltage	V_{DS}	V_{GS} = 0 V, I_D = -250 µA	-30	-	-	V
V_{DS} temperature coefficient	$\Delta V_{DS}/T_J$	I_D = -250 µA	-	-23	-	mV/°C
$V_{GS(th)}$ temperature coefficient	$\Delta V_{GS(th)}/T_J$		-	1.5	-	
Gate-source threshold voltage	$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = -250 µA	-0.6	-	-1.1	V
Gate-source leakage	I_{GSS}	V_{DS} = 0 V, V_{GS} = ± 12 V	-	-	± 100	nA
Zero gate voltage drain current	I_{DSS}	V_{DS} = -30 V, V_{GS} = 0 V	-	-	-1	µA
		V_{DS} = -30 V, V_{GS} = 0 V, T_J = 55 °C	-	-	-10	
On-state drain current [a]	$I_{D(on)}$	$V_{DS} \leq$ -5 V, V_{GS} = -10 V	-10	-	-	A
Drain-source on-state resistance [a]	$R_{DS(on)}$	V_{GS} = -10 V, I_D = -3 A	-	0.052	0.064	Ω
		V_{GS} = -4.5 V, I_D = -2 A	-	0.062	0.078	
		V_{GS} = -2.5 V, I_D = -1 A	-	0.090	0.120	
Forward transconductance [a]	g_{fs}	V_{DS} = -15 V, I_D = -3 A	-	10	-	S
Dynamic [b]						
Input capacitance	C_{iss}	V_{DS} = -15 V, V_{GS} = 0 V, f = 1 MHz	-	575	-	pF
Output capacitance	C_{oss}		-	60	-	
Reverse transfer capacitance	C_{rss}		-	51	-	
Total gate charge	Q_g	V_{DS} = -15 V, V_{GS} = -10 V, I_D = -4.3 A	-	14	21	nC
		V_{DS} = -15 V, V_{GS} = -4.5 V, I_D = -4.3 A	-	6.6	10	
Gate-source charge	Q_{gs}		-	1.2	-	
Gate-drain charge	Q_{gd}		-	1.9	-	
Gate resistance	R_g	f = 1 MHz	1.1	5.5	11	Ω
Turn-on delay time	$t_{d(on)}$	V_{DD} = -15 V, R_L = 4.4 Ω, $I_D \cong$ -3.4 A, V_{GEN} = -4.5 V, R_g = 1 Ω	-	15	30	ns
Rise time	t_r		-	18	35	
Turn-off delay time	$t_{d(off)}$		-	22	40	
Fall time	t_f		-	10	20	
Turn-on delay time	$t_{d(on)}$	V_{DD} = -15 V, R_L = 4.4 Ω, $I_D \cong$ -3.4 A, V_{GEN} = -10 V, R_g = 1 Ω	-	5	10	
Rise time	t_r		-	10	20	
Turn-off delay time	$t_{d(off)}$		-	22	40	
Fall time	t_f		-	10	20	
Drain-Source Body Diode Characteristics						
Continuous source-drain diode current	I_S	T_C = 25 °C	-	-	-4.5	A
Pulse diode forward current	I_{SM}		-	-	-15	
Body diode voltage	V_{SD}	I_S = -3.4 A, V_{GS} = 0 V	-	-0.89	-1.2	V
Body diode reverse recovery time	t_{rr}	I_F = -3.4 A, di/dt = 100 A/µs, T_J = 25 °C	-	20	40	ns
Body diode reverse recovery charge	Q_{rr}		-	10	20	nC
Reverse recovery fall time	t_a		-	9	-	ns
Reverse recovery rise time	t_b		-	11	-	

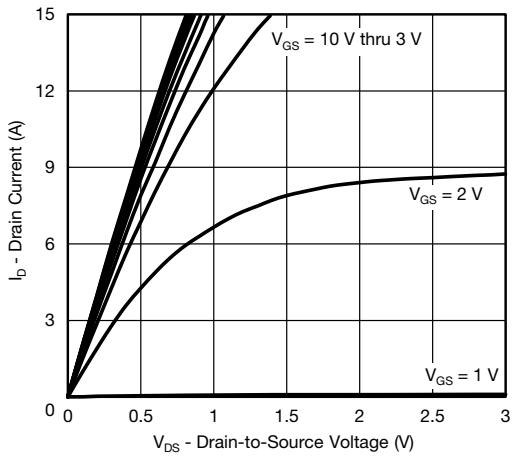
Notes

a. Pulse test; pulse width ≤ 300 µs, duty cycle ≤ 2 %

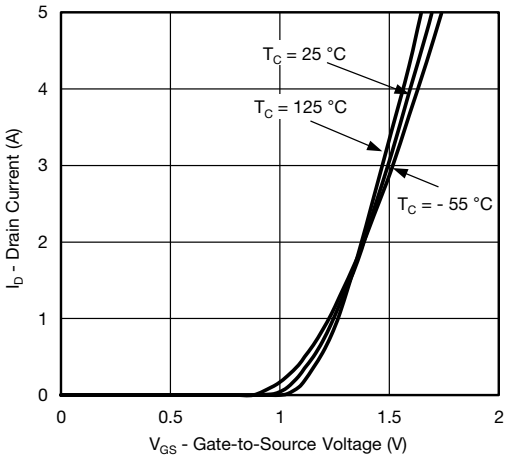
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

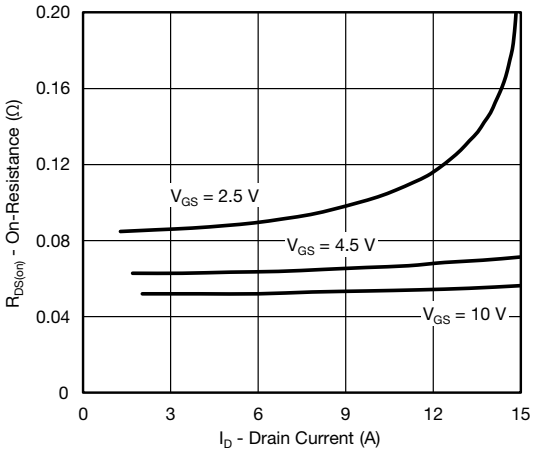
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



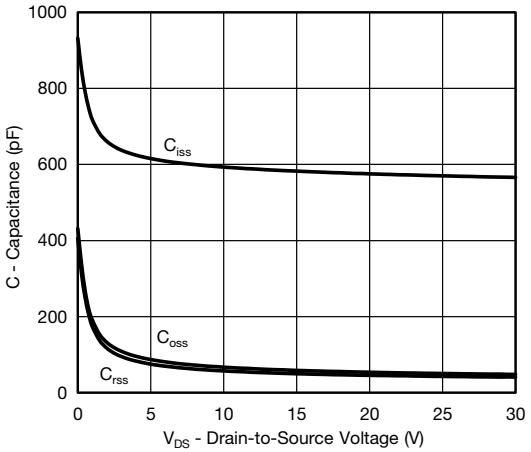
Output Characteristics



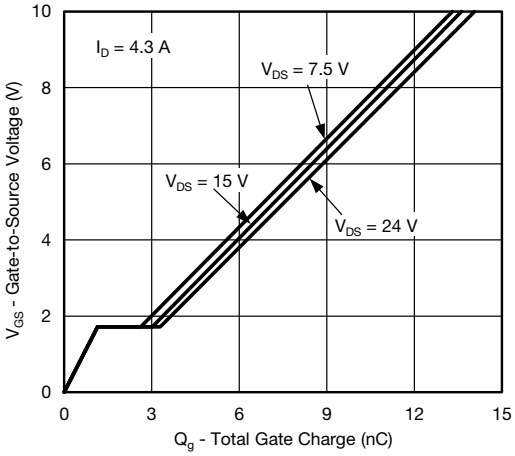
Transfer Characteristics



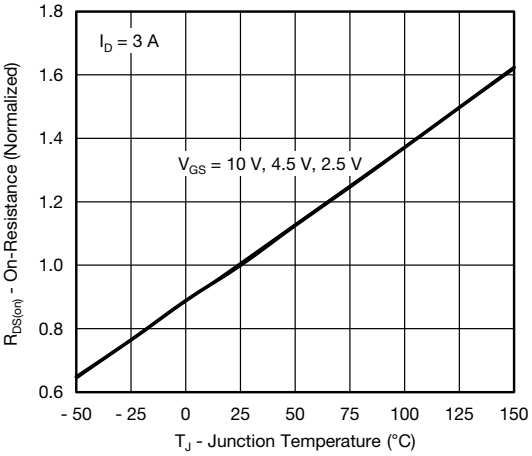
On-Resistance vs. Drain Current and Gate Voltage



Capacitance

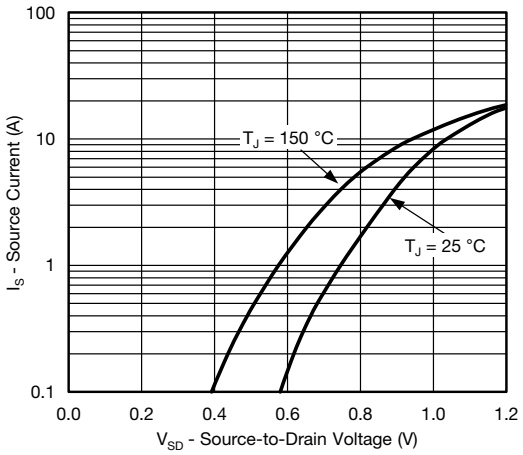


Gate Charge

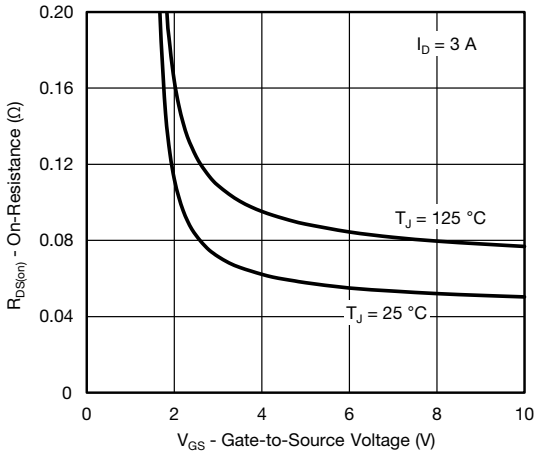


On-Resistance vs. Junction Temperature

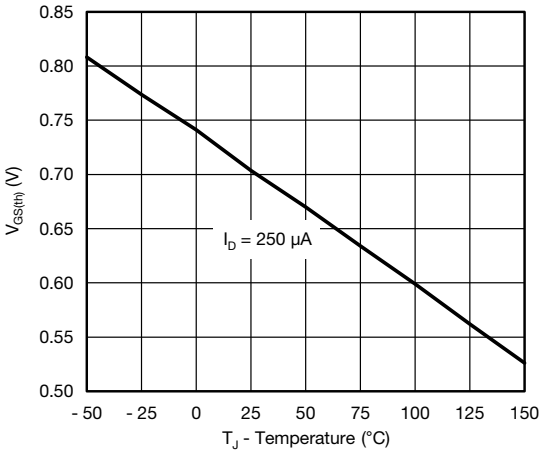
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



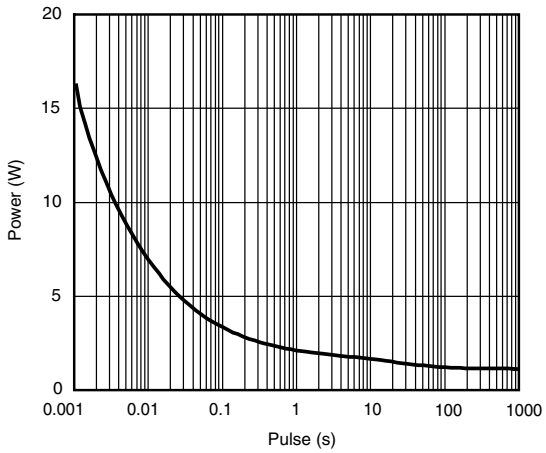
Source-Drain Diode Forward Voltage



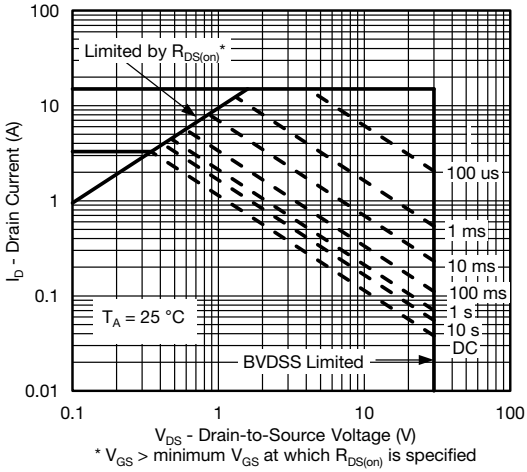
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

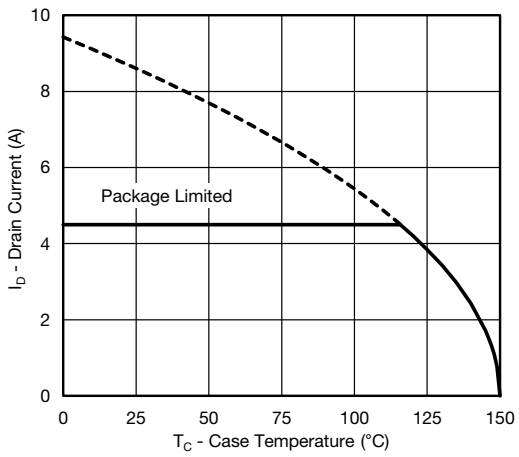


Single Pulse Power, Junction-to-Ambient

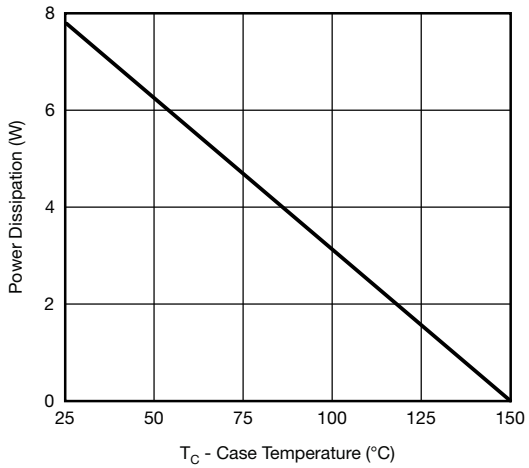


Safe Operating Area, Junction-to-Ambient

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Current Derating [a]

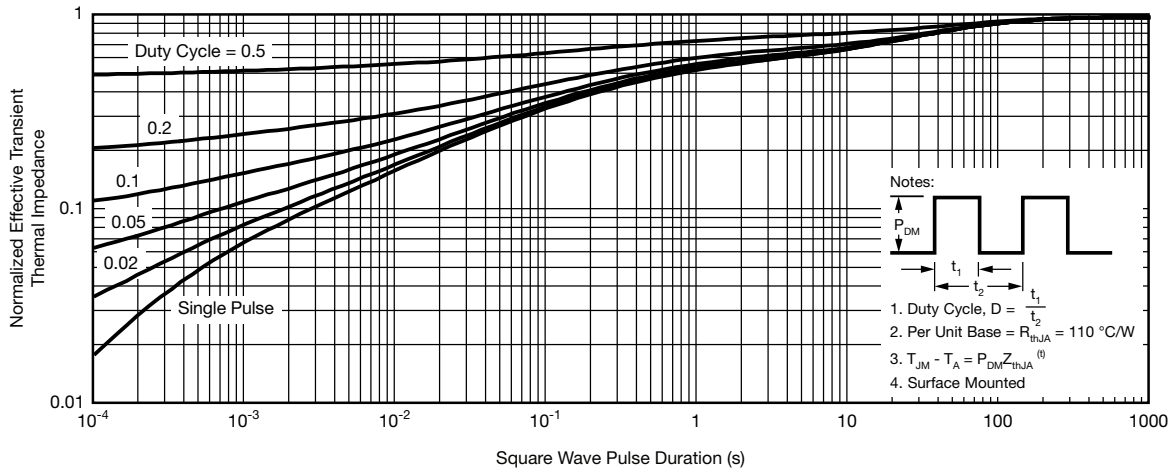


Power Derating

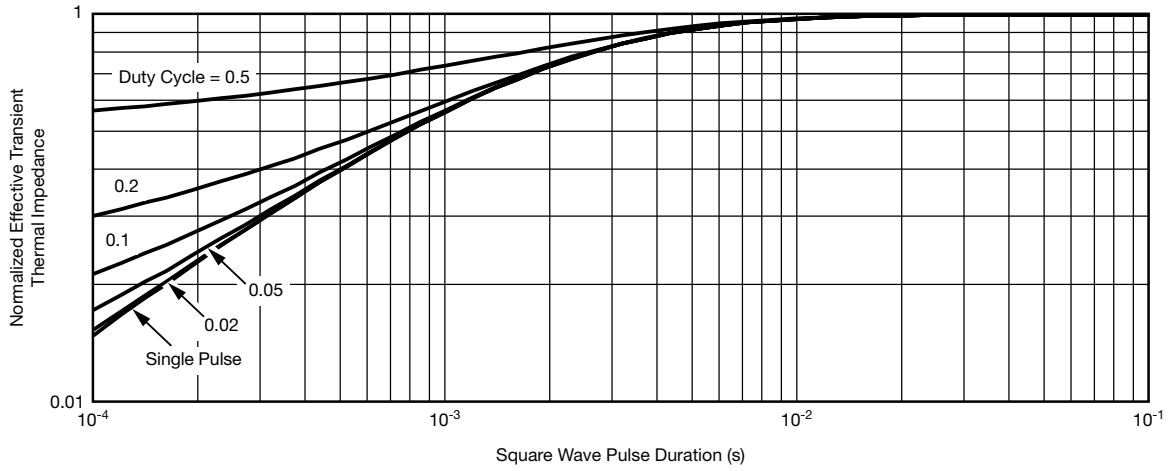
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



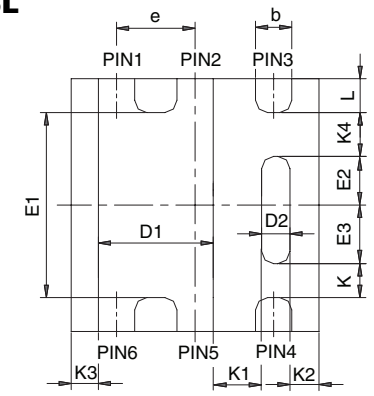
Normalized Thermal Transient Impedance, Junction-to-Ambient



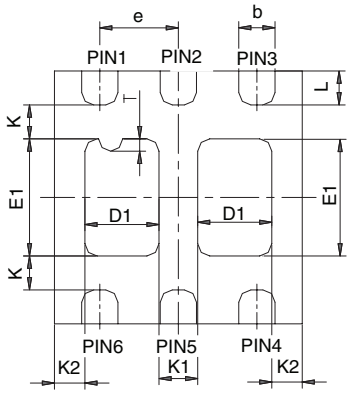
Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?63398.

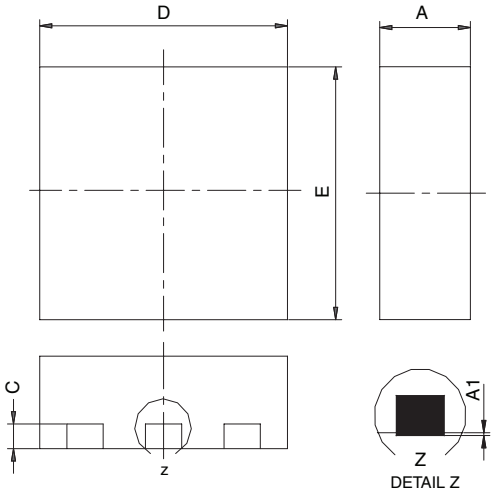
PowerPAK® SC70-6L



BACKSIDE VIEW OF SINGLE



BACKSIDE VIEW OF DUAL



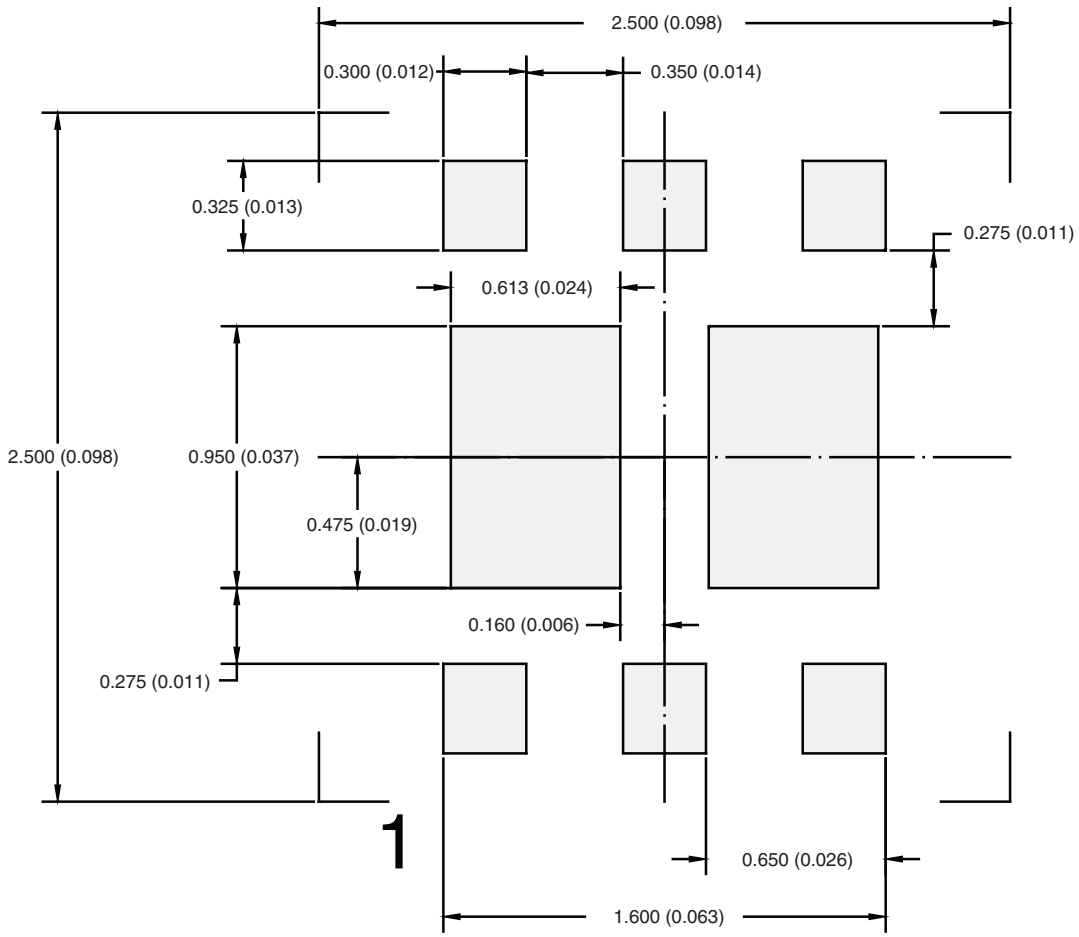
DETAIL Z

Notes:
1. All dimensions are in millimeters
2. Package outline exclusive of mold flash and metal burr
3. Package outline inclusive of plating

DIM	SINGLE PAD						DUAL PAD					
	MILLIMETERS			INCHES			MILLIMETERS			INCHES		
	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max	Min	Nom	Max
A	0.675	0.75	0.80	0.027	0.030	0.032	0.675	0.75	0.80	0.027	0.030	0.032
A1	0	-	0.05	0	-	0.002	0	-	0.05	0	-	0.002
b	0.23	0.30	0.38	0.009	0.012	0.015	0.23	0.30	0.38	0.009	0.012	0.015
C	0.15	0.20	0.25	0.006	0.008	0.010	0.15	0.20	0.25	0.006	0.008	0.010
D	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
D1	0.85	0.95	1.05	0.033	0.037	0.041	0.513	0.613	0.713	0.020	0.024	0.028
D2	0.135	0.235	0.335	0.005	0.009	0.013						
E	1.98	2.05	2.15	0.078	0.081	0.085	1.98	2.05	2.15	0.078	0.081	0.085
E1	1.40	1.50	1.60	0.055	0.059	0.063	0.85	0.95	1.05	0.033	0.037	0.041
E2	0.345	0.395	0.445	0.014	0.016	0.018						
E3	0.425	0.475	0.525	0.017	0.019	0.021						
e	0.65 BSC			0.026 BSC			0.65 BSC			0.026 BSC		
K	0.275 TYP			0.011 TYP			0.275 TYP			0.011 TYP		
K1	0.400 TYP			0.016 TYP			0.320 TYP			0.013 TYP		
K2	0.240 TYP			0.009 TYP			0.252 TYP			0.010 TYP		
K3	0.225 TYP			0.009 TYP								
K4	0.355 TYP			0.014 TYP								
L	0.175	0.275	0.375	0.007	0.011	0.015	0.175	0.275	0.375	0.007	0.011	0.015
T							0.05	0.10	0.15	0.002	0.004	0.006

ECN: C-07431 – Rev. C, 06-Aug-07
DWG: 5934

RECOMMENDED PAD LAYOUT FOR PowerPAK® SC70-6L Dual



Dimensions in mm (inches)

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